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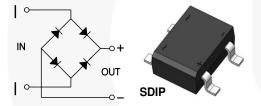


June 2015

# DF005S1 - DF10S1 Bridge Rectifier

#### **Features**

- Maximum Surge Rating:  $I_{FSM} = 35 \text{ A}$  $I^2t = 5.1 \text{ A}^2\text{Sec}$
- Optimized V<sub>F</sub>: Typical 0.95 V at 1 A, 25°C
- · DF10S Socket Compatible
- · Glass Passivated Junctions
- Lead Free Compliant to EU RoHS 2002/95/EU Directives
- · Green Molding Compound: IEC61249
- · Qualified with IR Reflow and Wave Soldering



## **Description**

With the ever-pressing need to improve power supply efficiency, improve surge rating, improve reliability, and reduce size, the DFxS1 family sets a new standard in performance and cost saving.

The DFxS1 family balances performance against cost. The design offers a moderate surge rating of 35 A required to handle inrush surge and maintain good reliability, with fair price.

The DFxS1 achieves good performance in a SDIP surface mount form factor, reducing board space and volumetric requirements vs. competitive devices.

# **Ordering Information**

Part Number	Top Mark	Package	Packing Method	
DF005S1	DF005S1	SDIP 4L	Tape and Reel	
DF01S1	DF01S1	SDIP 4L	Tape and Reel	
DF02S1	DF02S1	SDIP 4L	Tape and Reel	
DF04S1	DF04S1	SDIP 4L	Tape and Reel	
DF06S1	DF06S1	SDIP 4L	Tape and Reel	
DF08S1	DF08S1	SDIP 4L	Tape and Reel	
DF10S1	DF10S1	SDIP 4L	Tape and Reel	

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}\text{C}$  unless otherwise noted.

Symbol	Parameter	Value						Unit	
		DF005S1	DF01S1	DF02S1	DF04S1	DF06S1	DF08S1	DF10S1	Jiii
V <sub>RRM</sub>	Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
V <sub>RMS</sub>	Maximum RMS Bridge Input Voltage	35	70	140	280	420	560	700	V
V <sub>DC</sub>	Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
I <sub>F(AV)</sub>	Maximum Average Forward Current T <sub>A</sub> = 40°C				1.0				Α
I <sub>FSM</sub>	Peak Forward Surge Current 8.3 ms Single Half-Sine Wave Superimposed on Rated Load(JEDEC Method)				35				А
T <sub>STG</sub>	Storage Temperature Range			-!	55 to +150	)			°C
T <sub>J</sub>	Operating Junction Temperature Range			-1	55 to +150	)			°C

#### Thermal Characteristics(1)

Symbol	Parameter Conditions		Max.	Unit
R <sub>θJA</sub>		Single-Die Measurement (Maximum Land Pattern: 13 x 13 mm)	65	°C/W
	Thermal Resistance, Junction to Ambient	Multi-Die Measurement (Maximum Land Pattern: 13 x 13 mm)	50	
		Multi-Die Measurement (Minimum Land Pattern: 1.3 x 1.5 mm)	105	
ΨJL	Thermal Characterization Parameter, Junction to Lead	Single-Die Measurement (Maximum and Minimum Land Pattern)	27	°C/W

#### Note:

1. The thermal resistances ( $R_{\theta JA} \& \psi_{JL}$ ) are characterized with the device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2, PCB size: 76.2 x 114.3 mm.

Heating effect from adjacent dice is considered and only two dices are powered at the same time.

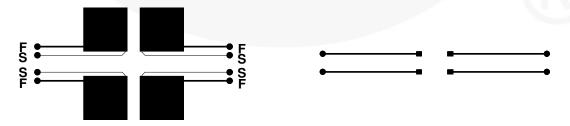


Figure 1. Maximum Pads of 2 oz Copper

Figure 2. Minimum Pads of 2 oz Copper

# **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V <sub>F</sub>	Forward Voltage Drop per Bridge Element	I <sub>F</sub> = 1.0 A			1.1	V
1	DC Reverse Current at Rated DC Blocking Voltage	$T_J = 25^{\circ}C$			3	μΑ
IR		T <sub>J</sub> = 125°C			500	
l <sup>2</sup> t	Rating for Fusing (t < 8.3 ms)				5.1	A <sup>2</sup> S
CJ	Junction Capacitance	V <sub>R</sub> = 4.0 V, f = 1.0 MHz		10		pF

## **Typical Performance Characteristics**

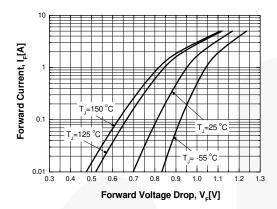


Figure 3. Typical Instantaneous Forward Characteristics

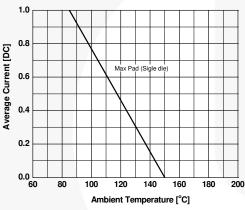


Figure 5. Maximum Average Current vs.
Ambient Temperature

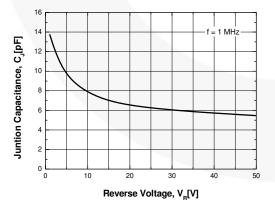


Figure 7. Typical Junction Capacitance

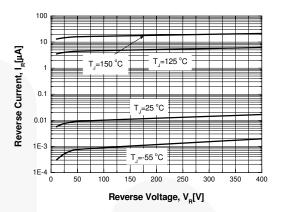


Figure 4. Typical Reverse Characteristics

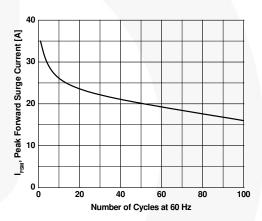
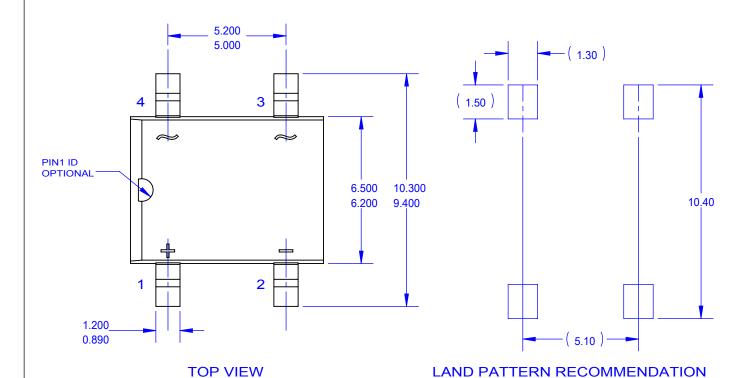
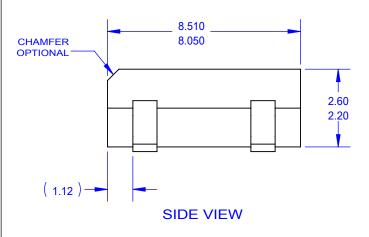
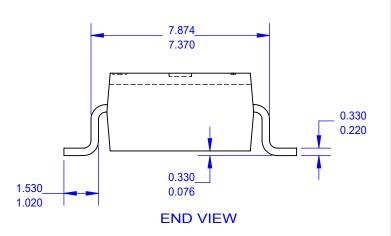


Figure 6. Peak Forward Surge Current vs.
Number of Cycles at 60Hz







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